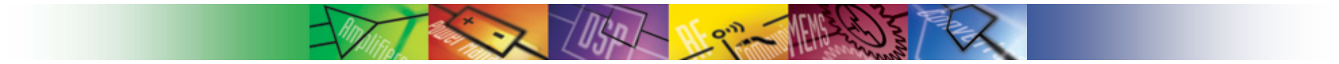

Product / Package Information

Package	LFCSP - Sawn - COL
Body Size (mm)	1.3 X 1.6 X 0.55
Lead Count	10
Terminal Finish	NiPdAu

Environmental Information

RoHS Compliant
High Temperature Compliant
Halogen Free Compliant
JIG Material Content Compliant

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	4.10E-04	80.80	808000	7.11	71116
Thermosets	Epoxy resin	Proprietary	4.56E-05	9.00	90000	0.79	7921
Thermosets	Phenol resin	Proprietary	2.54E-05	5.00	50000	0.44	4401
Other inorganic materials	Metal Hydroxide	Proprietary	2.54E-05	5.00	50000	0.44	4401
Other inorganic materials	Carbon black	1333-86-4	1.01E-06	0.20	2000	0.02	176
Subtotal			5.07E-04	100.00	1000000	8.80	88015

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	4.48 E-03	96.20	962000	77.74	777394
Copper & its alloys	Nickel	7440-02-0	1.40 E-04	3.00	30000	2.42	24243
Copper & its alloys	Silicon	7440-21-3	3.03 E-05	0.65	6500	0.53	5253
Copper & its alloys	Magnesium	7439-95-4	6.98 E-06	0.15	1500	0.12	1212
Subtotal			4.66 E-03	100.00	1000000	80.81	808102

Internal / External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Nickel & its alloys	Nickel	7440-02-0	8.60 E-05	97.3	972697	1.49	14929
Precious metals	Palladium	7440-05-3	2.00 E-06	2.3	22621	0.03	347
Precious metals	Gold	7440-57-5	4.14 E-07	0.5	4683	0.01	72
Subtotal			8.84 E-05	100.00	1000000	1.53	15349

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	7.20 E-05	100.0	1000000	1.25	12499

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	7.20 E-05	100.0	1000000	1.25	12499

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.56 E-04	70.0	700000	4.45	44476
Thermoset	Resin	Proprietary	5.49 E-05	15.0	150000	0.95	9531
Others	Additive	Proprietary	3.66 E-05	10.0	100000	0.64	6354
Other organic materials	Bisphenol A Glycidylether	25068-38-6	1.83 E-05	5.0	50000	0.32	3177
Subtotal			3.66 E-04	100.0	1000000	6.35	63537

	Weight (g)	Percentage (%)	PPM
Package Totals	**5.76 E-03**	**100.00**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability tc
any inaccuracy of such information.

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